



Product Change Notification: CENO-24TXFU730

Date:

30-Jun-2026

Product Category:

16-Bit Microcontrollers, Digital Signal Controllers

Notification Subject:

CCB 8368 Final Notice: Qualification of MMT as an additional assembly site for selected PIC24EP64GP203, dsPIC33EP64MC203, dsPIC33EP64MC503, dsPIC33EP64GP503, PIC24EP64MC203, PIC24EP32MC203, PIC24EP32GP203, dsPIC33EP32MC503, dsPIC33EP32GP503, dsPIC33EP16GS202, dsPIC33EP32GS202, dsPIC33EV64GM103, dsPIC33EV128GM003, dsPIC33EV32GM103, dsPIC33EV64GM003, dsPIC33EV128GM103, dsPIC33EV32GM003, dsPIC33EV256GM103 and dsPIC33EV256GM003 device families available in 28L UQFN (4x4x0.6mm) and 36L UQFN (5x5x0.6mm) packages.

Affected CPNs:

[CENO-24TXFU730_Affected_CPN_06302026.pdf](#)

[CENO-24TXFU730_Affected_CPN_06302026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MMT as an additional assembly site for selected PIC24EP64GP203, dsPIC33EP64MC203, dsPIC33EP64MC503, dsPIC33EP64GP503, PIC24EP64MC203, PIC24EP32MC203, PIC24EP32GP203, dsPIC33EP32MC503, dsPIC33EP32GP503, dsPIC33EP16GS202, dsPIC33EP32GS202, dsPIC33EV64GM103, dsPIC33EV128GM003, dsPIC33EV32GM103, dsPIC33EV64GM003, dsPIC33EV128GM103, dsPIC33EV32GM003, dsPIC33EV256GM103 and dsPIC33EV256GM003 device families available in 28L UQFN (4x4x0.6mm) and 36L UQFN (5x5x0.6mm) packages.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change
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						(Yes/No)
Assembly Site	ASE Inc.(ASE)		ASE Inc.(ASE)		Microchip Technology Thailand (Branch) (MMT)	Yes
Wire Material	CuPdAu		CuPdAu		CuPdAu	No
Die Attach Material	FH-900 (PFAS-free)		FH-900 (PFAS-free)		ATB-F125E1 (PFAS-free)	Yes
Molding Compound Material	For 28L: EME-G700L A	For 36L: CEL-9240HF	For 28L: EME-G700L A	For 36L: CEL-9240HF	For 28L and 36L: G700LTD	Yes
Lead-Frame Material	C7025		C7025		EFTEC64T	Yes
Lead-Frame Paddle Size	For 28L: 83 x 83 mils		For 28L: 83 x 83 mils		For 28L: 110 x 110 mils	Yes
Lead Lock	No		No		Yes (Locking hole)	Yes
Lead-Frame Design	See Pre and Post Change Summary attachment for comparison.					Yes

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery and manufacturability by qualifying MMT as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 17 July 2026 (date code: 2629)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	June 2026					July 2026			
Work Week	23	24	25	26	27	28	29	30	31
Qual Report Availability					x				
Final PCN Issue Date					x				
Estimated Implementation Date							x		

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Note: This is a qualification by similarity (QBS) to CCBs 7727 and 7764.001.

Revision History:

June 30, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_CENO-24TXFU730-Pre and Post Change Summary.pdf

PCN_CENO-24TXFU730-Qual Report-CCB 7727.pdf

PCN_CENO-24TXFU730-Qual Report-CCB 7764.001.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN):

DSPIC33EV128GM103-I/M5
DSPIC33EV32GM103-E/M5
DSPIC33EV32GM003-E/M5
DSPIC33EV64GM003-H/M5
DSPIC33EV128GM103-H/M5
DSPIC33EP64MC203-E/M5
DSPIC33EP64MC503-E/M5
DSPIC33EP64GP503-E/M5
PIC24EP64MC203-E/M5
DSPIC33EP64MC203-I/M5
DSPIC33EP64MC503-I/M5
DSPIC33EP64GP503-I/M5
PIC24EP64MC203-I/M5
PIC24EP32MC203-H/M5
PIC24EP32GP203-E/M5
DSPIC33EP32MC503-H/M5
DSPIC33EP32GP503-H/M5
DSPIC33EV64GM003-E/M5
DSPIC33EV128GM103-E/M5
PIC24EP64GP203-H/M5
DSPIC33EP64MC203-H/M5
DSPIC33EP64MC503-H/M5
DSPIC33EP64GP503-H/M5
PIC24EP64MC203-H/M5
PIC24EP32MC203-E/M5
PIC24EP32GP203-H/M5
DSPIC33EP16GS202-E/M6
DSPIC33EP32GS202-I/M6
DSPIC33EP16GS202-I/M6
DSPIC33EP16GS202T-E/M6
DSPIC33EV32GM103-H/M5
DSPIC33EV64GM103-H/M5

CENO-24TXFU730 - CCB 8368 Final Notice: Qualification of MMT as an additional assembly site for selected PIC24EP64GP203, dsPIC33EP64MC203, dsPIC33EP64MC503, dsPIC33EP64GP503, PIC24EP64MC203, PIC24EP32MC203, PIC24EP32GP203, dsPIC33EP32MC503, dsPIC33EP32GP503, dsPIC33EP16GS202, dsPIC33EP32GS202, dsPIC33EV64GM103, dsPIC33EV128GM003,

DSPIC33EV128GM003-E/M5

DSPIC33EV64GM003-I/M5

DSPIC33EV32GM003-H/M5

DSPIC33EV256GM103-H/M5

DSPIC33EV256GM003-H/M5

DSPIC33EV256GM003T-I/M5

DSPIC33EV256GM103-E/M5

DSPIC33EV256GM003-E/M5

DSPIC33EV256GM103-I/M5

DSPIC33EV256GM003-I/M5

DSPIC33EV256GM103T-I/M5

DSPIC33EP32MC503-I/M5

DSPIC33EV64GM103T-I/M5

DSPIC33EV128GM003-I/M5

DSPIC33EP32GP503-I/M5

PIC24EP32MC203-I/M5

PIC24EP32GP203-I/M5

DSPIC33EP32MC503-E/M5

DSPIC33EP32GP503-E/M5

PIC24EP64GP203-E/M5

PIC24EP64GP203-I/M5

DSPIC33EV64GM103-E/M5

DSPIC33EV32GM103-I/M5

DSPIC33EV32GM003-I/M5

DSPIC33EV64GM103-I/M5

DSPIC33EP32GS202-E/M6

DSPIC33EV128GM003-H/M5

DSPIC33EV128GM103T-I/M5

DSPIC33EV128GM003T-I/M5

DSPIC33EV32GM103T-I/M5

DSPIC33EV64GM003T-I/M5

DSPIC33EV32GM003T-I/M5

DSPIC33EP32GS202T-E/M6

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DSPIC33EP16GS202T-I/M6

DSPIC33EP32GS202T-E/M6C01

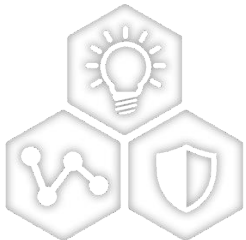
CENO-24TXFU730 - CCB 8368 Final Notice: Qualification of MMT as an additional assembly site for selected PIC24EP64GP203, dsPIC33EP64MC203, dsPIC33EP64MC503, dsPIC33EP64GP503, PIC24EP64MC203, PIC24EP32MC203, PIC24EP32GP203, dsPIC33EP32MC503, dsPIC33EP32GP503, dsPIC33EP16GS202, dsPIC33EP32GS202, dsPIC33EV64GM103, dsPIC33EV128GM003,

DSPIC33EP32GS202-E/M6C01

CCB 8368
Pre and Post Change Summary
PCN #: CENO-24TXFU730

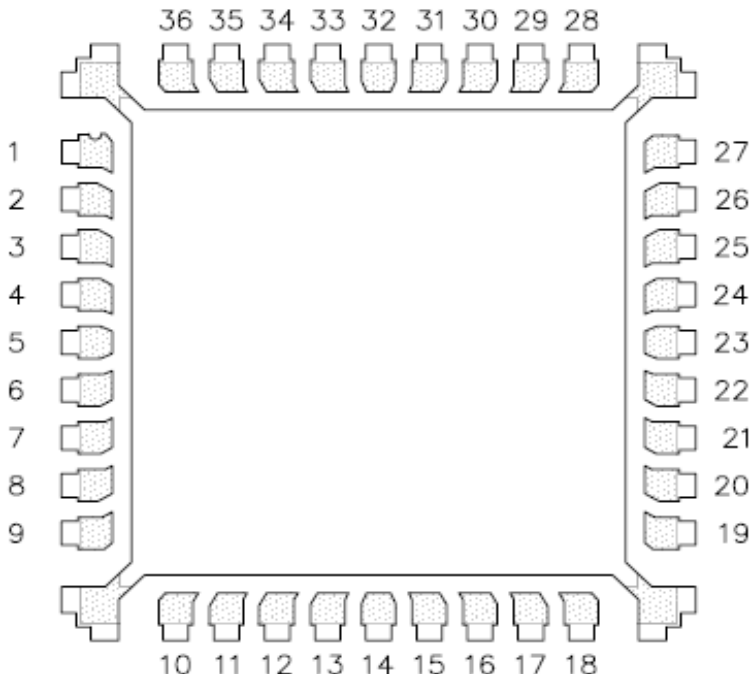
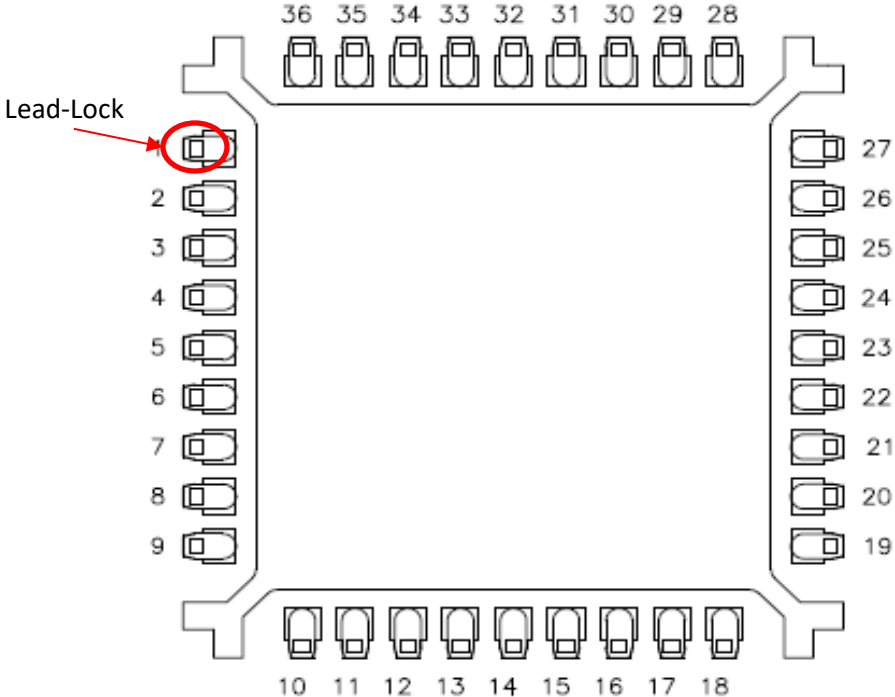


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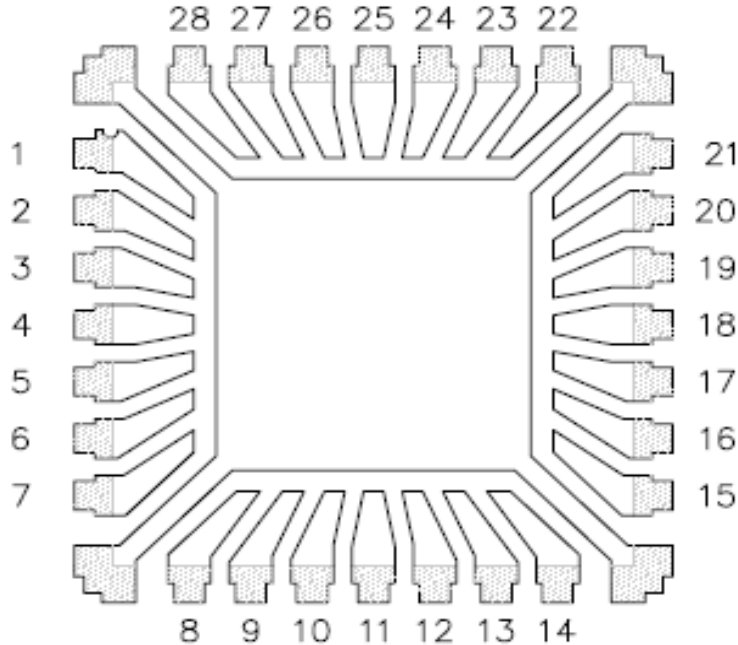
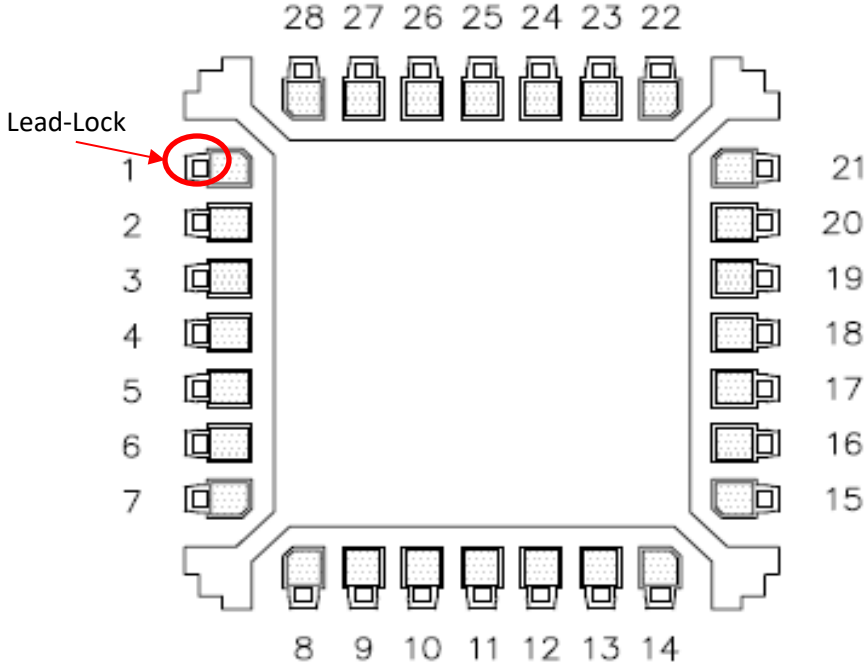
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Lead Frame Comparison – 36L UQFN (5x5x0.6mm)

ASE		MMT	
			
Lead-Frame Material	C7025	Lead-Frame Material	EFTEC64T
Lead-Frame Paddle Size	154 x 154 mils	Lead-Frame Paddle Size	154 x 154 mils
Lead-Lock	No	Lead-Lock	Yes (Locking hole)

Note 1 : Mold compound material fills the lead-lock hole, which provides improved protection against moisture penetration along the edge of the leads (pins) of the package.
2 Note 2 : Not to scale

Lead Frame Comparison – 28L UQFN (4x4x0.6mm)

ASE		MMT	
			
Lead-Frame Material	C7025	Lead-Frame Material	EFTEC64T
Lead-Frame Paddle Size	83 x 83 mils	Lead-Frame Paddle Size	110 x 110 mils
Lead-Lock	No	Lead-Lock	Yes (Locking hole)

Note 1 : Mold compound material fills the lead-lock hole, which provides improved protection against moisture penetration along the edge of the leads (pins) of the package.

3 Note 2 : Not to scale



Qualification Report Summary

RELIABILITY LABORATORY

PCN #: CENO-24TXFU730

Date: December 22, 2025

Qualification of MMT as an additional assembly site for selected PIC24EP64GP203, dsPIC33EP64MC203, dsPIC33EP64MC503, dsPIC33EP64GP503, PIC24EP64MC203, PIC24EP32MC203, PIC24EP32GP203, dsPIC33EP32MC503, dsPIC33EP32GP503, dsPIC33EP16GS202, dsPIC33EP32GS202, dsPIC33EV64GM103, dsPIC33EV128GM003, dsPIC33EV32GM103, dsPIC33EV64GM003, dsPIC33EV128GM103, dsPIC33EV32GM003, dsPIC33EV256GM103 and dsPIC33EV256GM003 device families available in 28L UQFN (4x4x0.6mm) and 36L UQFN (5x5x0.6mm) packages.

PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of MMT as an additional assembly site for selected PIC24EP64GP203, dsPIC33EP64MC203, dsPIC33EP64MC503, dsPIC33EP64GP503, PIC24EP64MC203, PIC24EP32MC203, PIC24EP32GP203, dsPIC33EP32MC503, dsPIC33EP32GP503, dsPIC33EP16GS202, dsPIC33EP32GS202, dsPIC33EV64GM103, dsPIC33EV128GM003, dsPIC33EV32GM103, dsPIC33EV64GM003, dsPIC33EV128GM103, dsPIC33EV32GM003, dsPIC33EV256GM103 and dsPIC33EV256GM003 device families available in 28L UQFN (4x4x0.6mm) and 36L UQFN (5x5x0.6mm) packages.

CN: E000282027
QUAL ID: R2501201 Rev. A
MP CODE: X0502YPRXVA1
Part No.: SST25WF080BT-40E/NP13GVAO
Bonding No.: BD-003276 Rev.01
CCB No.: 7727

Lead Frame

Paddle Size: Chip on Lead design
Material: EFTEC-64T
Surface: Ag on lead only
Process: Etched
Lead Lock: No
Part Number: 10100875
Plating Composition: Matte Tin

Bond Wire

Wire: Au wire

Die Attach Material

Epoxy: ATB F125E

Mold Compound

Mold Compound: G700LTD

Package

Type: 8L UDFN
Package Size: 2 x 3

PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.
MMT-262100588.000	GC01922438819.610
MMT-262100880.000	GC01922438819.610
MMT-262100881.000	GC01922438819.610

Result: **Pass**

Conclusion:

8L UDFN (2x3) assembled by MMT pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Precondition Prior Perform Reliability Tests (At MSL Level 1)	Electrical Test: +25°C, 85°C and 125°C System: NEXTEST_PV2	JESD22-A113	693(0)	0/693	Pass	Good Devices
	Bake 150°C, 24 hrs. System: CHINEE	JIP/IPC/JEDEC J-STD-020E		693		
	85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243			693		
	Electrical Test: +25°C, 85°C and 125°C System: NEXTEST_PV2		693(0)	0/693	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Temp Cycle	Stress Condition: -55°C to +150°C, 1000 Cycles System: TABAI ESPEC TSA-70H	JESD22-A104	231	231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C, 85°C and 125°C System: NEXTEST_PV2		231(0)	0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (>2.50 grams)		15(0)	0/15	Pass	Wire pull after Temp Cycle

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
UNBIASED-HAST	Stress Condition: +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22-A118	231	231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: NEXTEST_PV2		231(0)	0/231	Pass	77 units / lot

PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
HAST	Stress Condition: +130°C/85%RH, 96 hrs. Bias Volt: 1.95 Volts System: HAST 6000X	JESD22-A110	231	231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C, 85°C and 125°C System: NEXTEST_PV2		231(0)	0/231	Pass	77 units / lot

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
High Temperature Storage Life	Stress Condition: Bake 175°C, 500 hrs. System: TPS Bake Oven	JESD22-A103	45	45		45 units
	Electrical Test: +25°C, 85°C and 125°C System: NEXTEST_PV2		45(0)	0/45	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Solderability Temp 245°C	Steam Aging: Temp 93°C, 8Hrs System: SAS-3000 Solder Dipping: Solder Temp. 245°C Solder material: Pb Free Sn 95.5Ag3.9 Cu0.6 System: ERS A RA 2200D Visual Inspection: External Visual Inspection	J-STD-002	22(0)	0/22	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Bond Strength Data Assembly	Wire Pull (>2.50 grams)	Mil. Std. 883-2011	30(0)	0/30	Pass	Wire pull & bond shear data assembly
	Bond Shear (>12.60 grams)	CDF-AEC-Q100 -001	30(0)	0/30	Pass	



Qualification Report Summary

RELIABILITY LABORATORY

PCN #: CENO-24TXFU730

Date: June 10, 2026

Qualification of MMT as an additional assembly site for selected PIC24EP64GP203, dsPIC33EP64MC203, dsPIC33EP64MC503, dsPIC33EP64GP503, PIC24EP64MC203, PIC24EP32MC203, PIC24EP32GP203, dsPIC33EP32MC503, dsPIC33EP32GP503, dsPIC33EP16GS202, dsPIC33EP32GS202, dsPIC33EV64GM103, dsPIC33EV128GM003, dsPIC33EV32GM103, dsPIC33EV64GM003, dsPIC33EV128GM103, dsPIC33EV32GM003, dsPIC33EV256GM103 and dsPIC33EV256GM003 device families available in 28L UQFN (4x4x0.6mm) and 36L UQFN (5x5x0.6mm) packages.

PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of MMT as an additional assembly site for selected PIC24EP64GP203, dsPIC33EP64MC203, dsPIC33EP64MC503, dsPIC33EP64GP503, PIC24EP64MC203, PIC24EP32MC203, PIC24EP32GP203, dsPIC33EP32MC503, dsPIC33EP32GP503, dsPIC33EP16GS202, dsPIC33EP32GS202, dsPIC33EV64GM103, dsPIC33EV128GM003, dsPIC33EV32GM103, dsPIC33EV64GM003, dsPIC33EV128GM103, dsPIC33EV32GM003, dsPIC33EV256GM103 and dsPIC33EV256GM003 device families available in 28L UQFN (4x4x0.6mm) and 36L UQFN (5x5x0.6mm) packages.

CN: E000287245
QUAL ID: R2501391 Rev. A
MP CODE: ZA702YS8BD00
Part No.: MCP16502TAD-E/S8B
Bonding No.: BD-000569 / Rev-05
CCB No.: 7764.001

Lead Frame

Paddle Size: 114 x 114
Material: C194
Surface: Ag ring plated DAP
Process: Etched
Lead Lock: YES
Part Number: 10103203
Plating Composition: Ag plated

Bond Wire

Wire: CuPdAu wire

Die Attach Material

Epoxy: 8006NS
Conductive No

Mold Compound

Mold Compound: G700LTD

Package

Type: 32L VQFN
Package Size: 5x5 mm

PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.
MMT-262601100.000
MMT-262601235.000
MMT-262700399.000

Result: **Pass**

Conclusion:

Qualification of ZA702 mask / MCP16502TAD-E/S8B product / CuPdAu wire in 32L VQFN 5x5 mm package at MMT site is qualified for MSL3 at 260°C as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards.

PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Moisture Soak Precondition Prior to Stresses	MSL3: 150°C 24 hours Bake, 192 hours Moisture Soak at 30°C/60%RH, 3x Reflow at 260°C Electrical Test: 25°C and 125°C System: ETS88	JESD22-A113, JEDEC J-STD-020	231 units each lot / 3 lots	0/231 (each lot)	Pass	Electrical Results (Fail/Pass): 0/231, 0/231, 0/231;

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
High Temp Storage	175°C / 500 hours Electrical Test: 25°C and 125°C System: ETS88	JESD22-A103	45 units each lot / 3 lots	0/45 (each lot)	Pass	Electrical Results (Fail/Pass): 0/45, 0/45, 0/45;

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Temperature Cycling (1000 Cycles)	-55°C / +150°C Air to Air / 1000 Cycles Electrical Test: 25°C and 125°C System: ETS88	JESD22-A104	77 units each lot / 3 lots	0/77 (each lot)	Pass	Electrical Results (Fail/Pass): 0/77, 0/77, 0/77; WBP (Fail/Pass): 0/3, 0/3, 0/3; WBS (Fail/Pass): 0/3, 0/3, 0/3;

PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Temperature Cycling (2000 Cycles)	-55°C / +150°C Air to Air / 2000 Cycles Electrical Test: 25°C and 125°C System: ETS88	JESD22-A104	77 units each lot / 3 lots	0/77 (each lot)	Pass	Electrical Results (Fail/Pass): 0/77, 0/77, 0/77; WBP (Fail/Pass): 0/3, 0/3, 0/3; WBS (Fail/Pass): 0/3, 0/3, 0/3;

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Biased HAST (96 hours)	+130°C / 85%RH / 96 hours / Bias Voltage: 5.5V Electrical Test: 25°C and 125°C System: ETS88	JESD22-A110	77 units each lot / 3 lots	0/77 (each lot)	Pass	Electrical Results (Fail/Pass): 0/77, 0/77, 0/77; WBP (Fail/Pass): 0/3, 0/3, 0/3; WBS (Fail/Pass): 0/3, 0/3, 0/3;

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Biased HAST (192 hours)	+130°C / 85%RH / 192 hours / Bias Voltage: 5.5V Electrical Test: 25°C and 125°C System: ETS88	JESD22-A110	77 units each lot / 3 lots	0/77 (each lot)	Pass	Electrical Results (Fail/Pass): 0/77, 0/77, 0/77; WBP (Fail/Pass): 0/3, 0/3, 0/3; WBS (Fail/Pass): 0/3, 0/3, 0/3;

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Unbiased HAST (96 hours)	+130°C / 85%RH / 96 hours Electrical Test: 25°C System: ETS88	JESD22-A118	77 units each lot / 3 lots	0/77 (each lot)	Pass	Electrical Results (Fail/Pass): 0/77, 0/77, 0/77

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Solderability (0 Hr) Method 1: Dip and Look	Pb-free 8 hours Steam age. Dip at 245°C, 100% leads >95% lead coverage	J-STD-002 / JESD22B-102	22 units / 1 lot	0/22	Pass	Visual Result (Fail/Pass): 0/22

PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Physical Dimension (0Hr)	Within package diagram dimension	JESD22 B100 and B108	10 units each lot / 3 lots	0/30	Pass	Result (Fail/Pass): 0/30

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Wire Pull	Bond Strength Data Assembly	Mil. Std. 883-2011	5 units / 1 lot	0/5	Pass	Result (Fail/Pass): 0/5

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Bond Shear	Bond Strength Data Assembly	CDF-AEC-Q100 -001	5 units / 1 lot	0/5	Pass	Result (Fail/Pass): 0/5